NXP

Final Product Change Notification 201503007F01

Issue Date: 25-Mar-2015
Effective Date: 07-Jul-2015

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QUALITY

Management Summary
BGA7210 and BGX7101 are qualified and released at subcon: ASEN for assembly and industrial testing, providing flexibility in supply to the customer, by releasing a second source.

Change Category

[ ] Wafer Fab process	[ ] Assembly Process	[ ] Product Marking	[ ] Design
[ ] Wafer Fab materials	[ ] Assembly Materials	[ ] Electrical spec./Test coverage	[ ] Mechanical Specification
[ ] Wafer Fab location	[X] Assembly Location	[X] Test Location	[ ] Packing/Shipping/Labeling

Qualification and release of BGA7210 and BGX7101 in assembly-site: ASEN as 2nd source

Details of this Change

This project has been started for BGA7210 and BGX7101, to assure additional industrial capacity, providing flexibility in supply to the customer by releasing a second source.

Why do we Implement this Change
Secure supply to the customer by releasing a second source for BGA7210 and BGX7101.

Identification of Affected Products
Top side marking
Line C of the marking for BGA7210 and BGX7101 will change:

BGA7210:
APK: TSDYWW1
ASEN: TXDYWW1

BGX7101:
APK: SDYWW1
ASEN: XDYWW1
Y is last digit of the year and WW is weekcode.

Product Availability

Sample Information
Samples availability differs by product - see attached sample plan
For BGA7210 from March 8th 2015
For BGX7101 form March 27th 2015
Production
Planned first shipment 28-Jun-2015

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

N.A.; APK assembly and testing will run parallel to second source assembly and final test at subcon: ASEN.

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 24-Apr-2015.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name	BL HPRF Quality Helpdesk
Position	Quality engineer & Customer support BL RF SS
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Customer Part#	Changed Part 12NC
BGA7210,515	935294197515